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November 2007

FDC365P

P-Channel PowerTrench[®] MOSFET -35V, -4.3A, $55m\Omega$

Features

- Max $r_{DS(on)} = 55m\Omega$ at $V_{GS} = -10V$, $I_D = -4.2A$
- Max $r_{DS(on)} = 80 \text{m}\Omega$ at $V_{GS} = -4.5 \text{V}$, $I_D = -3.2 \text{A}$
- RoHS Compliant

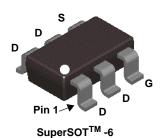
General Description

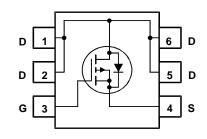
This P-Channel MOSFET has been produced using Fairchild Semiconductor's proprietary PowerTrench technology to deliver low $r_{DS(on)}$ and optimized Bvdss capability to offer superior performance benefit in the applications.

Applications

- Inverter
- Power Supplies







MOSFET Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter		Ratings	Units	
V_{DS}	Drain to Source Voltage		-35	V	
V_{GS}	Gate to Source Voltage		±20	V	
I _D	-Continuous	(Note 1a)	-4.3	Δ.	
	-Pulsed		-20	A	
Б	Power Dissipation	(Note 1a)	1.6	10/	
P_{D}	Power Dissipation	(Note 1b)	0.8	W	
T _J , T _{STG}	Operating and Storage Junction Temperature Range		-55 to +150	°C	

Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	78	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1b)	156	C/VV

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
.365P	FDC365P	SSOT6	7"	8mm	3000 units

Electrical Characteristics $T_J = 25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	acteristics					
BV _{DSS}	Drain to Source Breakdown Voltage	$I_D = -250 \mu A, V_{GS} = 0 V$	-35			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I_D = -250 μ A, referenced to 25°C		-26		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -28V, V_{GS} = 0V$			-1	μΑ
I _{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20V, V_{DS} = 0V$			±100	nA

On Characteristics

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = -250 \mu A$	-1	-1.8	-3	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I _D = -250μA, referenced to 25°C		5.0		mV/°C
		$V_{GS} = -10V, I_D = -4.2A$		45	55	
r _{DS(on)}	r _{DS(on)} Static Drain to Source On Resistance	$V_{GS} = -4.5V, I_D = -3.2A$		70	80	mΩ
		$V_{GS} = -10V, I_D = -4.2A, T_J = 125$ °C		69	90	
9 _{FS}	Forward Transconductance	$V_{DS} = -10V, I_{D} = -4.2A$		8.7		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V 20V V 0V	530	705	pF
C _{oss}	Output Capacitance	$V_{DS} = -20V, V_{GS} = 0V,$ f = 1MHz	105	135	pF
C _{rss}	Reverse Transfer Capacitance	1 - 11/11/2	55	80	pF
R_g	Gate Resistance	f = 1MHz	6.1		Ω

Switching Characteristics

t _{d(on)}	Turn-On Delay Time	$V_{DD} = -20V, I_{D} = -4.2A, V_{GS} = -10V, R_{GEN} = 6\Omega$		7	13	ns
t _r	Rise Time			3	10	ns
t _{d(off)}	Turn-Off Delay Time	V _{GS} = -10V, K _{GEN} = 612		15	28	ns
t _f	Fall Time			3	10	ns
Q_{g}	Total Gate Charge	V _{GS} = 0V to -10V		11	15	nC
Q_{g}	Total Gate Charge	$V_{GS} = 0V \text{ to -5V}$ $V_{DD} = -20V_{DD}$,	6	9	nC
Q _{gs}	Gate to Source Charge	I _D = -4.2A		1.7		nC
Q_{gd}	Gate to Drain "Miller" Charge			2.2		nC

Drain-Source Diode Characteristics

V_{SD}	Source to Drain Diode Forward Voltage	$V_{GS} = 0V, I_S = -1.3A$ (Note 2)		-0.8	-1.2	V
t _{rr}	Reverse Recovery Time	L = 4.24 di/dt = 1004/vs		16	29	ns
Q _{rr}	Reverse Recovery Charge	I _F = -4.2A, di/dt = 100A/μs		7	14	nC

Notes:

Rouse. Is Rouse, is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. Rouc is guaranteed by design while Rouse is determined by the user's board design.



a.78°C/W when mounted on a 1 in² pad of 2 oz copper on FR-4 board.



b.156°C/W when mounted on a minimum pad of 2 oz copper.

^{2:} Pulse Test: Pulse Width < 300μ s, Duty cycle < 2.0%.

Typical Characteristics T_J = 25°C unless otherwise noted

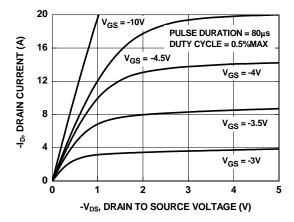


Figure 1. On-Region Characteristics

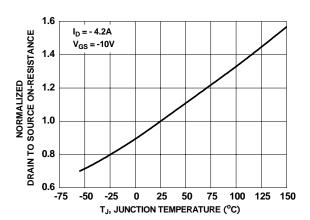


Figure 3. Normalized On-Resistance vs Junction Temperature

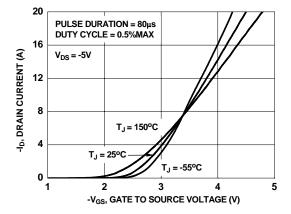


Figure 5. Transfer Characteristics

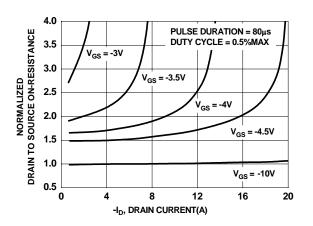


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

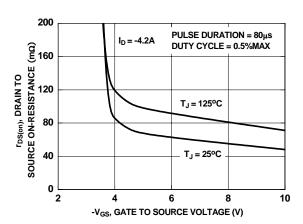


Figure 4. On-Resistance vs Gate to Source Voltage

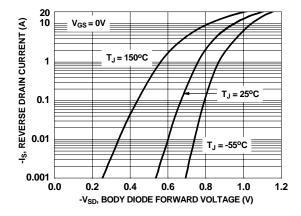


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics T_J = 25°C unless otherwise noted

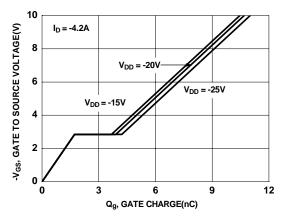


Figure 7. Gate Charge Characteristics

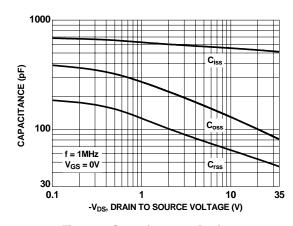


Figure 8. Capacitance vs Drain to Source Voltage

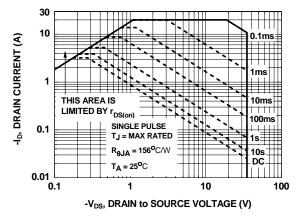


Figure 9. Forward Bias Safe Operating Area

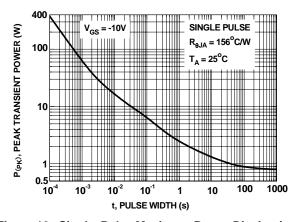


Figure 10. Single Pulse Maximum Power Dissipation

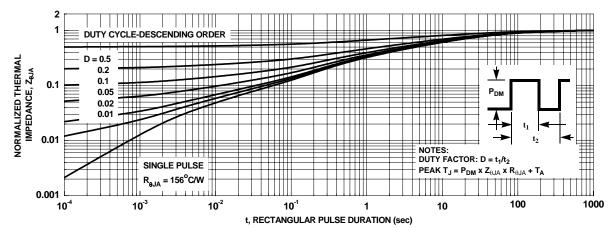
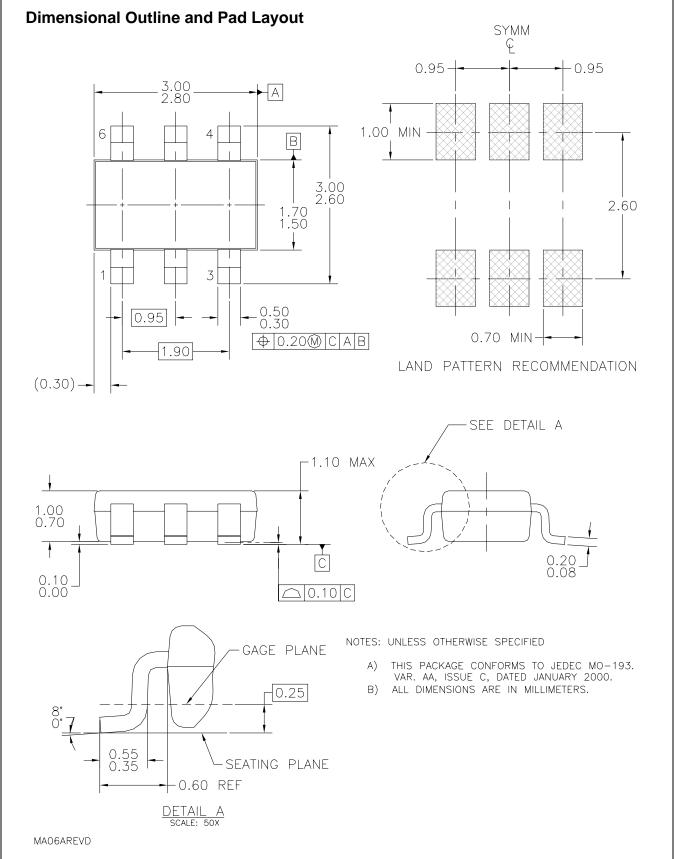


Figure 11. Transient Thermal Response Curve



Preliminary Datasheet



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